

Gap Pad® 1500

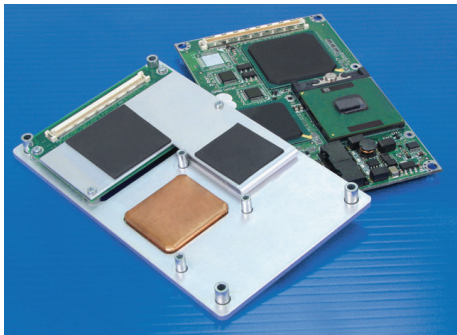
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PRODUCT DESCRIPTION

Thermally Conductive, Un-Reinforced Gap Filling Material

FEATURES AND BENEFITS

- Thermal conductivity: 1.5 W/m-K
- Un-reinforced construction for additional compliancy
- Conformable, low hardness
- Electrically isolating



Gap Pad® 1500 has an ideal filler blend that gives it a low-modulus characteristic that maintains optimal thermal performance yet still allows for easy handling. The natural tack on both sides of the material allows for good compliance to adjacent surfaces of components, minimizing interfacial resistance.

Note: To build a part number, visit our website at www.bergquistcompany.com.

TYPICAL PROPERTIES OF GAP PAD 1500

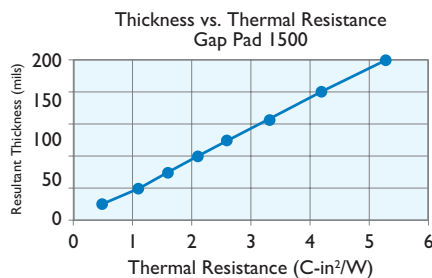
PROPERTY	IMPERIAL VALUE	METRIC VALUE	TEST METHOD	
Color	Black	Black	Visual	
Reinforcement Carrier	—	—	—	
Thickness (inch) / (mm)	0.020 to 0.200	0.508 to 5.080	ASTM D374	
Inherent Surface Tack (1 sided)	2	2	—	
Density (Bulk Rubber) (g/cc)	2.1	2.1	ASTM D792	
Heat Capacity (J/g-K)	1.0	1.0	ASTM E1269	
Hardness (Bulk Rubber) (Shore 00) (1)	40	40	ASTM D2240	
Young's Modulus (psi) / (kPa) (2)	45	310	ASTM D575	
Continuous Use Temp (°F) / (°C)	-76 to 392	-60 to 200	—	
ELECTRICAL				
Dielectric Breakdown Voltage (Vac)	>6000	>6000	ASTM D149	
Dielectric Constant (1000 Hz)	5.5	5.5	ASTM D150	
Volume Resistivity (Ohm-meter)	10 ¹¹	10 ¹¹	ASTM D257	
Flame Rating	V-O	V-O	U.L. 94	
THERMAL				
Thermal Conductivity (W/m-K)	1.5	1.5	ASTM D5470	
THERMAL PERFORMANCE vs. STRAIN				
	Deflection (% strain)	10	20	30
	Thermal Impedance (°C-in ² /W) 0.040" (3)	1.62	1.50	1.33
1) Thirty second delay value Shore 00 hardness scale. 2) Young's Modulus, calculated using 0.01 in/min. step rate of strain with a sample size of 0.79 inch ³ . 3) The ASTM D5470 test fixture was used. The recorded value includes interfacial thermal resistance. These values are provided for reference only. Actual application performance is directly related to the surface roughness, flatness and pressure applied.				

TYPICAL APPLICATIONS INCLUDE

- Telecommunications
- Computer and peripherals
- Power conversion
- RDRAM™ memory modules/chip scale packages
- Areas where heat needs to be transferred to a frame chassis or other type of heat spreader

CONFIGURATIONS AVAILABLE

- Sheet form and die-cut parts



Disclaimer

Note:

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